



Product Change Notification

Change Notification #: 118322-00
Change Title: Select Intel® Xeon® Gold and Intel® Xeon® Platinum Processors
PCN 118322-00, Manufacturing Site, Label
Add Third site (Costa Rica) for Assembly
Date of Publication: June 18, 2021

Key Characteristics of the Change:

Manufacturing Site, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	August 23, 2021
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Description of Change to the Customer:

Intel is certifying an additional Manufacturing Site in Costa Rica to enable full flow manufacturing (Assembly, Test, and Finish) for the products listed in the Products Affected / Intel Ordering Codes table below. The Costa Rica Manufacturing site was previously qualified for Test and Finish operations only.

Costa Rica Assembly operations will begin on the date specified in the Forecasted Key Milestones table above. Customers may expect to receive goods from Costa Rica in addition to the existing previously qualified manufacturing sites.

The shipping box labels will represent the Country of Origin, depending on the site which performed assembly. Please refer to the example label images below.

Example only to show Malaysia as Country of Origin

(P) CUST PROD:	(1B) BOX: RLP00008
(V) SUPPLIER: 04195 INTEL	
(1P) IPN: INTEL PRODUCT NAMEXX	
(S) SPEC: S 1234 (30P) MM#: 123456	
(1T) LOT: FPO NUMBER	(Q) QTY: 12345 (9D) DATE: YYWW
(1T) LOT:	(Q) QTY: (9D) DATE:
RoHS COMPLIANT, e1	

MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 09DEC08

ASSEMBLED IN MALAYSIA

Example only to show Costa Rica as Country of Origin

(P) CUST PROD:		(1B) BOX: RLX00040
(V) SUPPLIER: 04195	INTEL	
(1P) IPN: INTEL PRODUCT NAMEXX		
(S) SPEC: S 1234	(30P) MM#: 123456	
(1T) LOT: FPO NUMBER	(Q) QTY: 12345	(SD) DATE: YYWW
(1T) LOT:	(Q) QTY:	(SD) DATE:
RoHS COMPLIANT: e1		

MAX REFLOW 260 °C
 TEMP
 LEVEL 3 HOURS 168
 BAG SEAL DATE 03JUN14

ASSEMBLED IN COSTA RICA

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, functionality, quality or reliability for the products. All manufacturing sites are certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change.

Customers should notify their receiving department to expect shipments from any one of our qualified manufacturing sites in Malaysia or Costa Rica.

Please contact your Intel Field Representative for any questions and concerns.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#
Intel® Xeon® Gold 6354 Processor	CD8068904571601	S RKH7	99A9D6
Intel® Xeon® Platinum 8368 Processor	CD8068904572001	S RKH8	99A9D7
Intel® Xeon® Gold 6330N Processor	CD8068904582501	S RKH9	99A9DF
Intel® Xeon® Platinum 8360Y Processor	CD8068904571901	S RKHF	99A9FT
Intel® Xeon® Platinum 8352Y Processor	CD8068904572401	S RKHG	99A9GC
Intel® Xeon® Gold 6314U Processor	CD8068904570101	S RKHL	99A9H7
Intel® Xeon® Gold 6330 Processor	CD8068904572101	S RKHM	99A9HG
Intel® Xeon® Gold 6346 Processor	CD8068904570201	S RKHN	99A9HL
Intel® Xeon® Gold 6348 Processor	CD8068904572204	S RKHP	99A9HV
Intel® Xeon® Platinum 8380 Processor	CD8068904572601	S RKHR	99A9J4
Intel® Xeon® Platinum 8368Q Processor	CD8068904582803	S RKHX	99A9JT
Intel® Xeon® Platinum 8358P Processor	CD8068904599101	S RKJ0	99A9KC
Intel® Xeon® Platinum 8358 Processor	CD8068904572302	S RKJ1	99A9KF
Intel® Xeon® Platinum 8352V Processor	CD8068904571501	S RKJ2	99A9KH
Intel® Xeon® Platinum 8351N Processor	CD8068904582702	S RKJ3	99A9KK
Intel® Xeon® Platinum 8352S Processor	CD8068904642802	S RKJ8	99A9LT
Intel® Xeon® Gold 6338 Processor	CD8068904572501	S RKJ9	99A9LX
Intel® Xeon® Gold 6338N Processor	CD8068904722302	S RKY2	99AHXL

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 18, 2021	00	Originally Published PCN



Product Change Notification

118322-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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